

HAT1036R

Silicon P Channel Power MOS FET Power Switching

REJ03G1149-0700

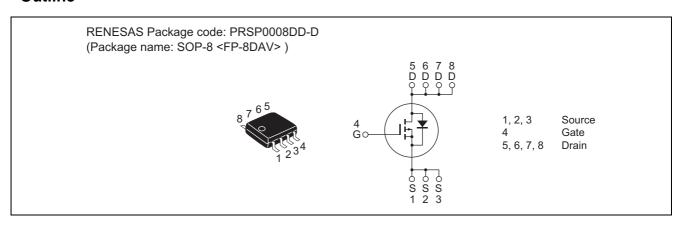
(Previous: ADE-208-662E)

Rev.7.00 Sep 07, 2005

Features

- Low on-resistance $R_{DS\;(on)} = 11\; m\Omega\; typ \label{eq:resistance}$
- Capable of –4 V gate drive
- Low drive current
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-30	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	-12	Α
Drain peak current	I _{D (pulse)} Note 1	-96	Α
Body-drain diode reverse drain current	I _{DR}	-12	Α
Channel dissipation	Pch Note 2	2.5	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. When using the glass epoxy board (FR4 $40\times40\times1.6$ mm), PW ≤10 s

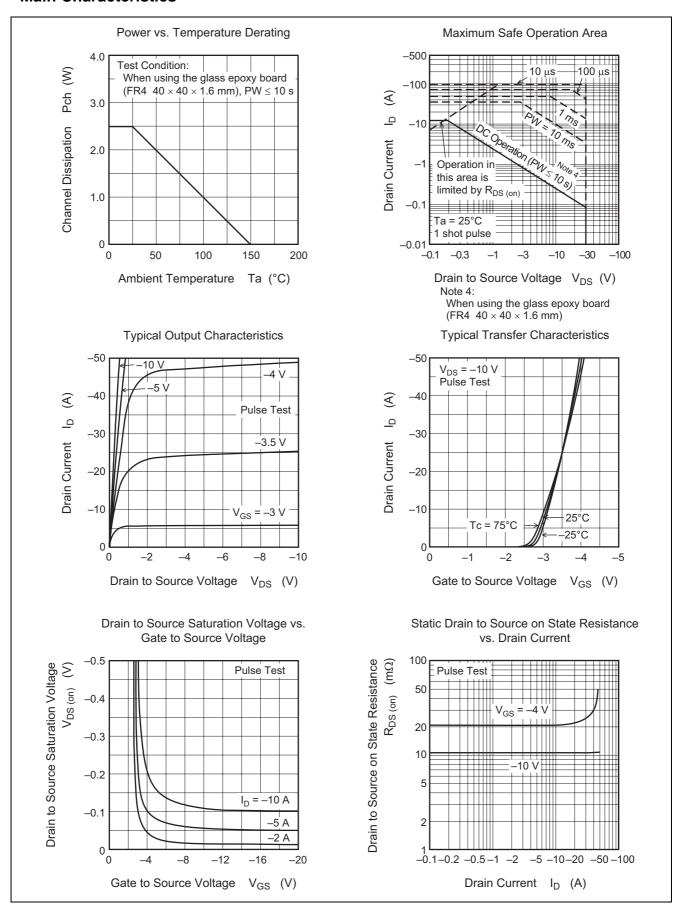
Electrical Characteristics

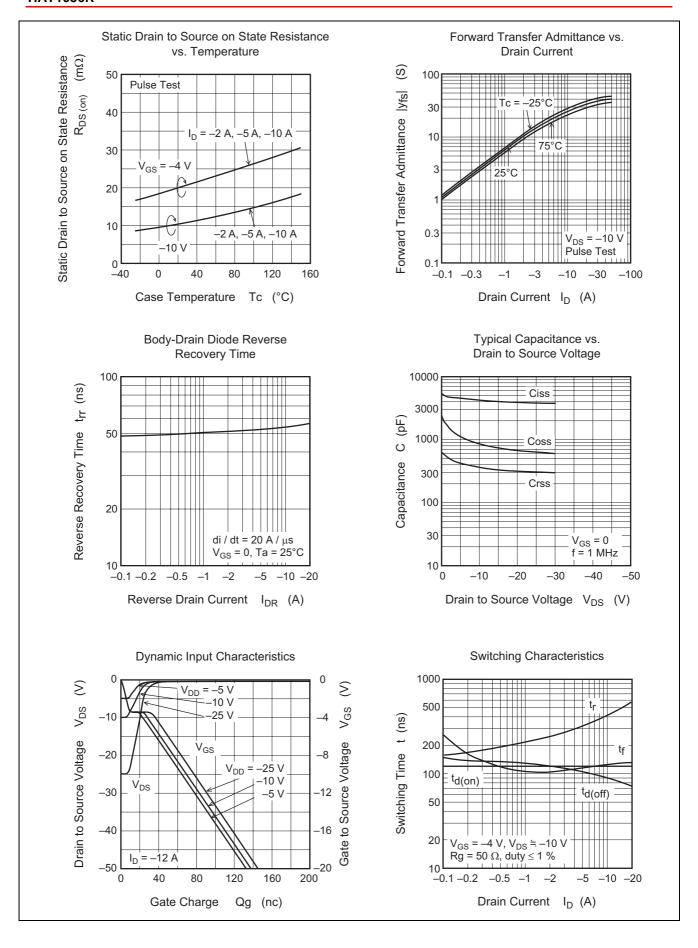
 $(Ta = 25^{\circ}C)$

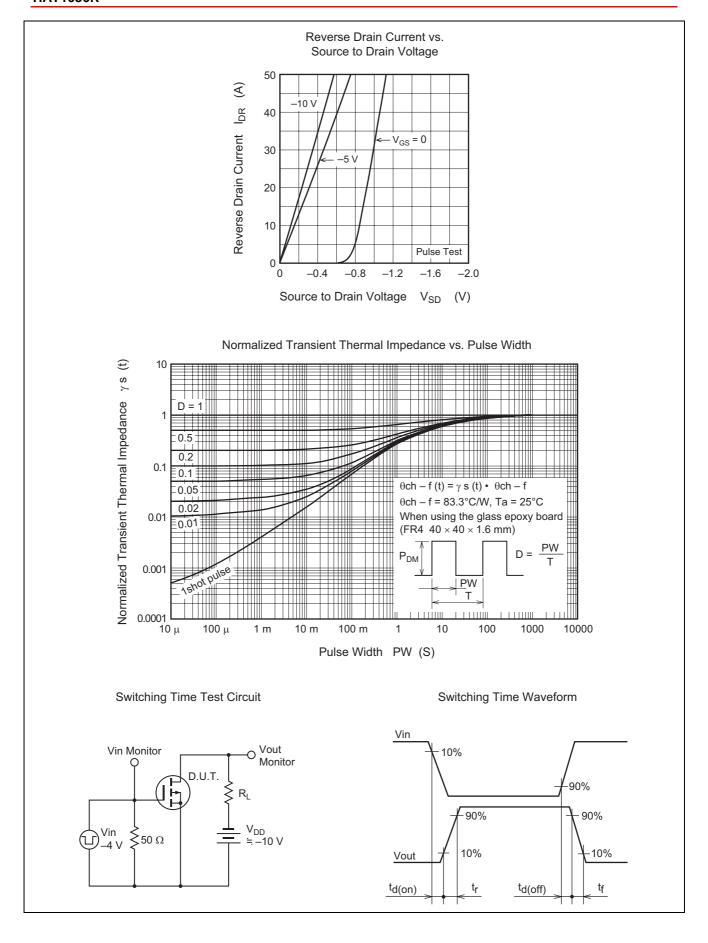
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	-30	_		>	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}		_	±0.1	μΑ	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}		_	-1	μΑ	$V_{DS} = -30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0	_	-2.5	>	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}	_	11	14	mΩ	$I_D = -6 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note } 3}$
	R _{DS (on)}	_	21	34	mΩ	$I_D = -6 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	12	20	_	S	$I_D = -6 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note } 3}$
Input capacitance	Ciss	_	4200	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	870	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	360	_	pF	f = 1 MHz
Total gate charge	Qg	_	70	_	nC	$V_{DD} = -10 \text{ V}$
Gate to source charge	Qgs	_	12	_	nC	V _{GS} = -10 V
Gate to drain charge	Qgd	_	14	_	nC	I _D = -12 A
Turn-on delay time	t _{d (on)}	_	120	_	ns	$V_{GS} = -4 \text{ V}, I_D = -6 \text{ A},$
Rise time	t _r	_	350	_	ns	V _{DD} ≅ −10 V
Turn-off delay time	t _{d (off)}	_	100	_	ns	
Fall time	t _f	_	120	_	ns	
Body-drain diode forward voltage	V_{DF}	_	-0.85	-1.11	V	$I_F = -12 \text{ A}, V_{GS} = 0^{\text{Note } 3}$
Body-drain diode reverse recovery time	t _{rr}	_	55	_	ns	$I_F = -12 \text{ A}, V_{GS} = 0$
						$di_F/dt = 20 A/\mu s$

Note: 3. Pulse test

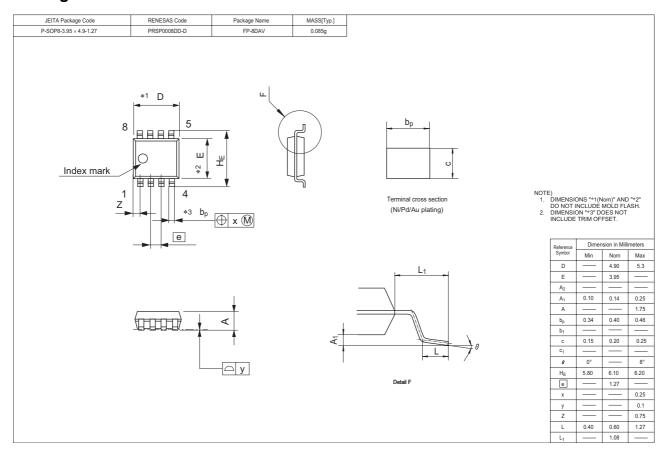
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT1036R-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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